



YOUSHANG SEMICONDUCTOR

**设计研发新型功率器件**

**各类小信号开关**

**中低压及高压大电流等场效应管**

0755-83047638

ysbdt@szyoushang.cn

www.szyoushang.cn



企业微信二维码



企业QQ二维码

## Description

This Bipolar Junction Transistor (BJT) is designed to meet the stringent requirements of Automotive Applications.

## Features

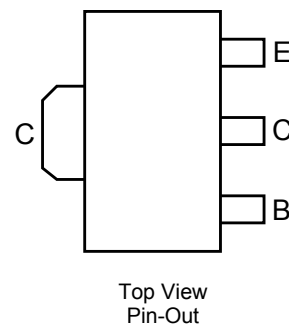
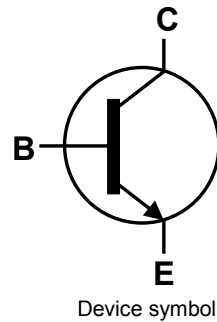
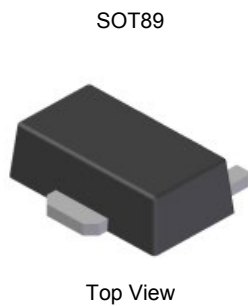
- $BV_{CEO} > 100V$
- $I_C = 1A$  high Continuous Current
- Low saturation voltage  $V_{CE(sat)} < 300mV @ 250mA$

## Mechanical Data

- Case: SOT89
- Case Material: Molded Plastic, "Green" Molding Compound
- Moisture Sensitivity: Level 1 per J-STD-020
- UL Flammability Rating 94V-0
- Terminals: Matte Tin Finish, Solderable per MIL-STD-202, Method 208 (E3)
- Weight: 0.052 grams (Approximate)

## Application

- Load management functions
- Solenoid, relay and actuator drivers
- DC – DC modules



**Absolute Maximum Ratings** (@  $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	$V_{CB0}$	120	V
Collector-Emitter Voltage	$V_{CEO}$	100	V
Emitter-Base Voltage	$V_{EBO}$	7	V
Continuous Collector Current	$I_C$	1	A
Peak Pulse Current	$I_{CM}$	2	A
Continuous Base Current	$I_B$	200	mA

**Thermal Characteristics** (@  $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

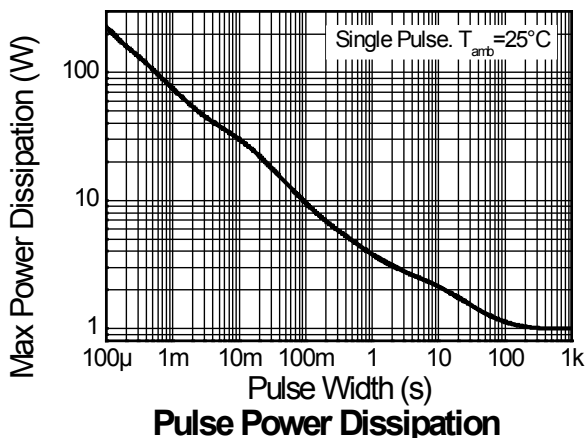
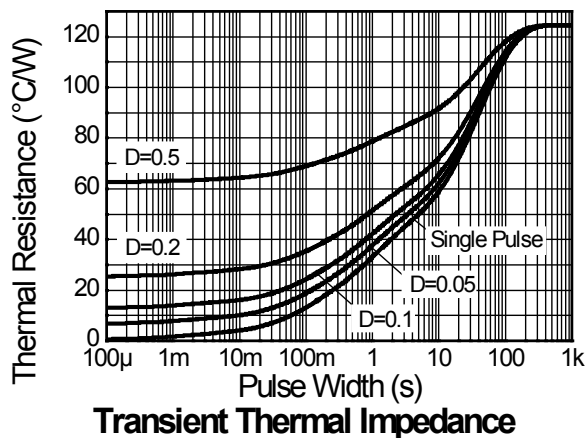
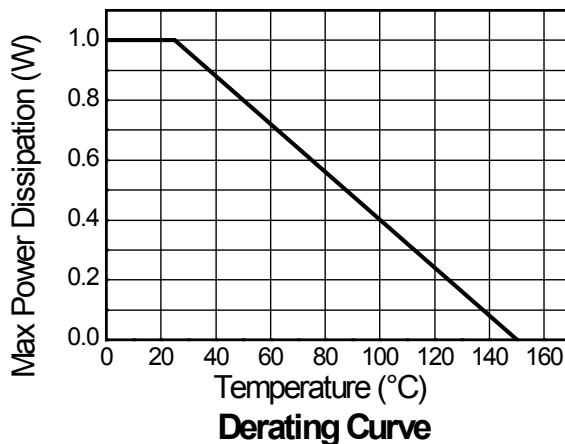
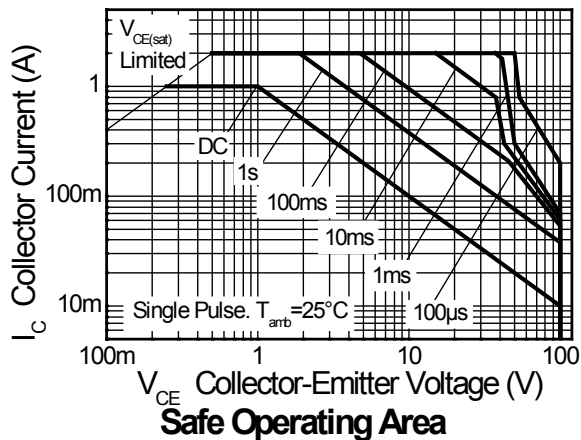
Characteristic	Symbol	Value	Unit
Collector Power Dissipation (Note 5)	$P_D$	1	W
Thermal Resistance, Junction to Ambient Air (Note 5)	$R_{\theta JA}$	125	$^\circ\text{C/W}$
Thermal Resistance, Junction to Leads (Note 6)	$R_{\theta JL}$	10.01	$^\circ\text{C/W}$
Operating and Storage Temperature Range	$T_{J, T_{STG}}$	-55 to +150	$^\circ\text{C}$

**ESD Ratings** (Note 7)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	C

Notes: 5. For the device mounted on 15mm x 15mm x 1.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions.  
 6. Thermal resistance from junction to solder-point (on the exposed collector pad).  
 7. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

## Thermal Characteristics and Derating Information

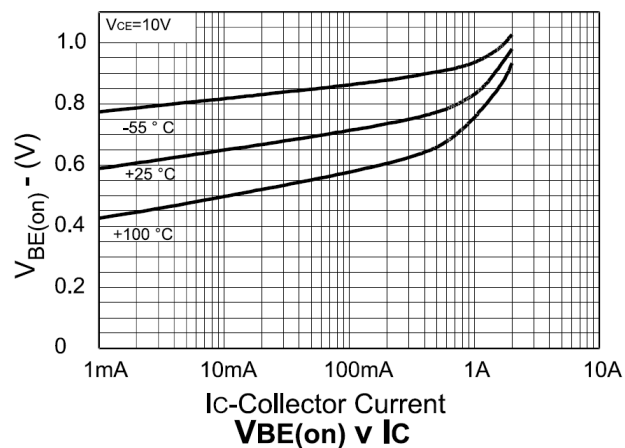
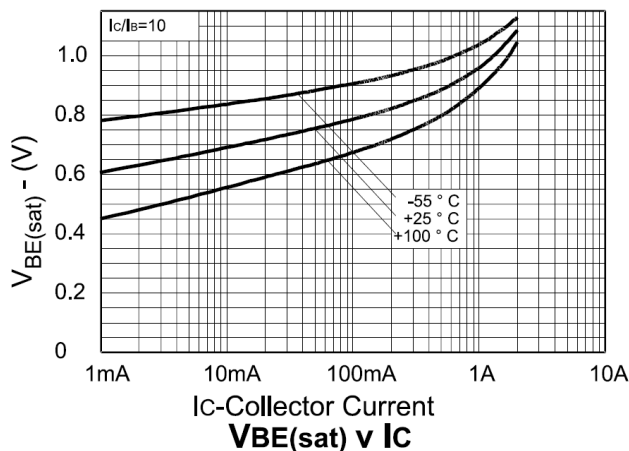
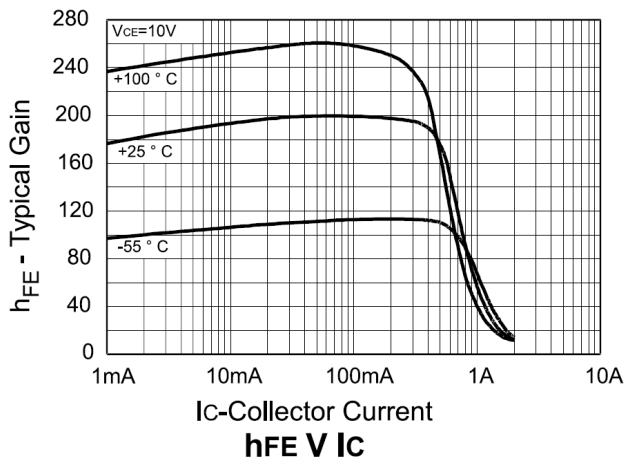
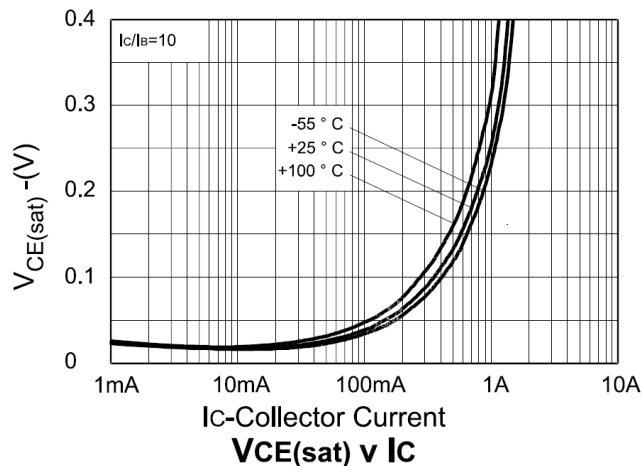
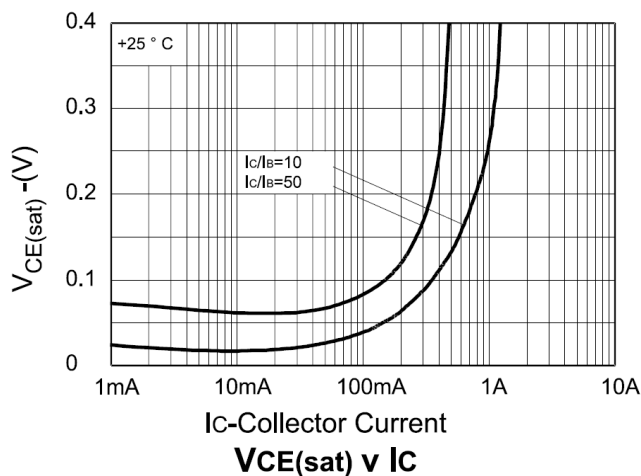


**Electrical Characteristics** (@  $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

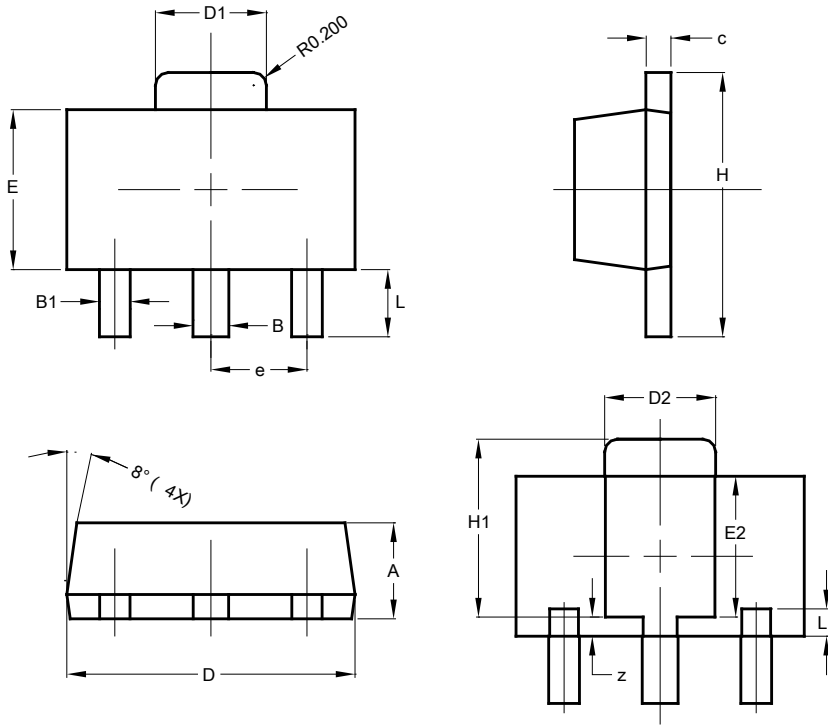
Characteristic	Symbol	Min	Typ.	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	$BV_{CBO}$	120	-	-	V	$I_C = 100\mu\text{A}$
Collector-Emitter Breakdown Voltage (Note 8)	$BV_{CEO}$	100	-	-	V	$I_C = 1\text{mA}$
Emitter-Base Breakdown Voltage	$BV_{EBO}$	7	-	-	V	$I_E = 100\mu\text{A}$
Collector Cutoff Current	$I_{CBO}$	-	-	100	nA	$V_{CB} = 100\text{V}$
Emitter Cutoff Current	$I_{EBO}$	-	-	100	nA	$V_{EB} = 5\text{V}$
Emitter Cutoff Current	$I_{CES}$	-	-	100	nA	$V_{CES} = 100\text{V}$
DC current transfer Static ratio (Note 8)	$h_{FE}$	100	-	-	-	$I_C = 1\text{mA}, V_{CE} = 10\text{V}$
		100	-	300		$I_C = 250\text{mA}, V_{CE} = 10\text{V}$
		60	-	-		$I_C = 500\text{mA}, V_{CE} = 10\text{V}$
		20	-	-		$I_C = 1\text{A}, V_{CE} = 10\text{V}$
Collector-Emitter Saturation Voltage (Note 8)	$V_{CE(sat)}$	-	-	0.3 0.6	V	$I_C = 500\text{mA}, I_B = 50\text{mA}$ $I_C = 1\text{A}, I_B = 100\text{mA}$
Base-Emitter Saturation Voltage (Note 8)	$V_{BE(sat)}$	-	-	1.15	V	$I_C = 1\text{A}, I_B = 100\text{mA}$
Base-Emitter Turn-on Voltage (Note 8)	$V_{BE(on)}$	-	-	1.0	V	$I_C = 1\text{A}, V_{CE} = 10\text{V}$
Transitional Frequency	$f_t$	150	-	-	MHz	$I_C = 50\text{mA}, V_{CE} = 10\text{V}$ $f = 100\text{MHz}$
Output capacitance	$C_{obo}$	-	-	10	pF	$V_{CB} = 10\text{V}, f = 1\text{MHz}$ ,

 Notes: 8. Measured under pulsed conditions. Pulse width  $\leq 300\mu\text{s}$ . Duty cycle  $\leq 2\%$ .

**Typical Electrical Characteristics** (@  $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

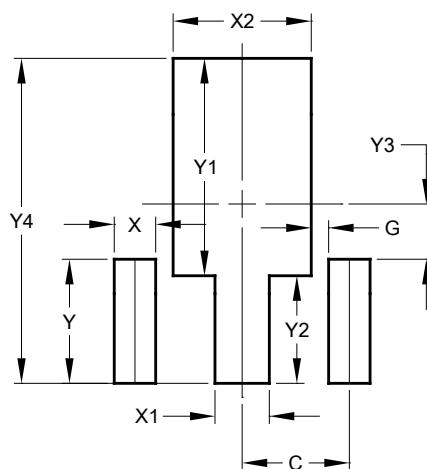


### Package Outline Dimensions



SOT89			
Dim	Min	Max	Typ
A	1.40	1.60	1.50
B	0.50	0.62	0.56
B1	0.42	0.54	0.48
c	0.35	0.43	0.38
D	4.40	4.60	4.50
D1	1.62	1.83	1.733
D2	1.61	1.81	1.71
E	2.40	2.60	2.50
E2	2.05	2.35	2.20
e	-	-	1.50
H	3.95	4.25	4.10
H1	2.63	2.93	2.78
L	0.90	1.20	1.05
L1	0.327	0.527	0.427
z	0.20	0.40	0.30
All Dimensions in mm			

### Suggested Pad Layout



Dimensions	Value (in mm)
C	1.500
G	0.244
X	0.580
X1	0.760
X2	1.933
Y	1.730
Y1	3.030
Y2	1.500
Y3	0.770
Y4	4.530